

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>WEI-CHENG WU</td> <td>09/27/2013</td> </tr> <tr> <td>YEN-HUEI CHEN</td> <td>09/27/2013</td> </tr> <tr> <td>HUNG-JEN LIAO</td> <td>10/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	WEI-CHENG WU	09/27/2013	YEN-HUEI CHEN	09/27/2013	HUNG-JEN LIAO	10/02/2013
Name	Execution Date								
WEI-CHENG WU	09/27/2013								
YEN-HUEI CHEN	09/27/2013								
HUNG-JEN LIAO	10/02/2013								
RECEIVING PARTY DATA									
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED								
Street Address:	NO. 8, LI-HSIN ROAD 6								
Internal Address:	HSIN-CHU SCIENCE PARK								
City:	HSIN-CHU								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14052745</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14052745				
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Application Number:	14052745								
CORRESPONDENCE DATA									
Fax Number:	(216)373-3450								
Phone:	2166540090								
Email:	docketing@cooperlegalgroup.com								
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>									
Correspondent Name:	COOPER LEGAL GROUP LLC								
Address Line 1:	6505 ROCKSIDE ROAD SUITE 330								
Address Line 4:	INDEPENDENCE, OHIO 44131								
ATTORNEY DOCKET NUMBER:	TSMC2013-0669								
NAME OF SUBMITTER:	MARCUS A. FISCHER								
Signature:	/Marcus A. Fischer/								

OP \$40.00 14052745

Date:

10/13/2013

Total Attachments: 2

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**ASSIGNMENT**

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Wei-Cheng Wu  
Hsinchu City, TW

Yen-Huei Chen  
Jhudong Township, TW

Hung-Jen Liao  
Hsin-Chu City, TW

NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Wei-Cheng Wu, Yen-Huei Chen and Hung-Jen Liao, by these present do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

**MEMORY ARRANGEMENT**

for which application for United States Letters Patent has been filed on \_\_\_\_\_ under Serial No. \_\_\_\_\_, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models,

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samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

<u>Wei-Cheng Wu</u> Inventor's Signature	<u>2013/9/27</u> Date
<u>Wei-Cheng Wu</u> Printed Name in English	

<u>Yen-Huei CHEN</u> Inventor's Signature	<u>2013/9/27</u> Date
<u>Yen-Huei Chen</u> Printed Name in English	

<u>Hung-Jen Liao</u> Inventor's Signature	<u>10/2/2013</u> Date
<u>Hung-Jen Liao</u> Printed Name in English	